

PS710E-1A, PS710EL-1A**6-PIN DIP, 0.08 Ω LOW ON-STATE RESISTANCE
2.0 A CONTINUOUS LOAD CURRENT
1-ch Optical Coupled MOS FET**

-NEPOC Series-

DESCRIPTION

The PS710E-1A and PS710EL-1A are solid state relays containing a GaAs LED on the input side and MOS FETs on the output side.

It is suitable for PLC, etc. because of its large continuous load current and low on-state resistance.

The PS710EL-1A has a surface mount type lead.

FEATURES

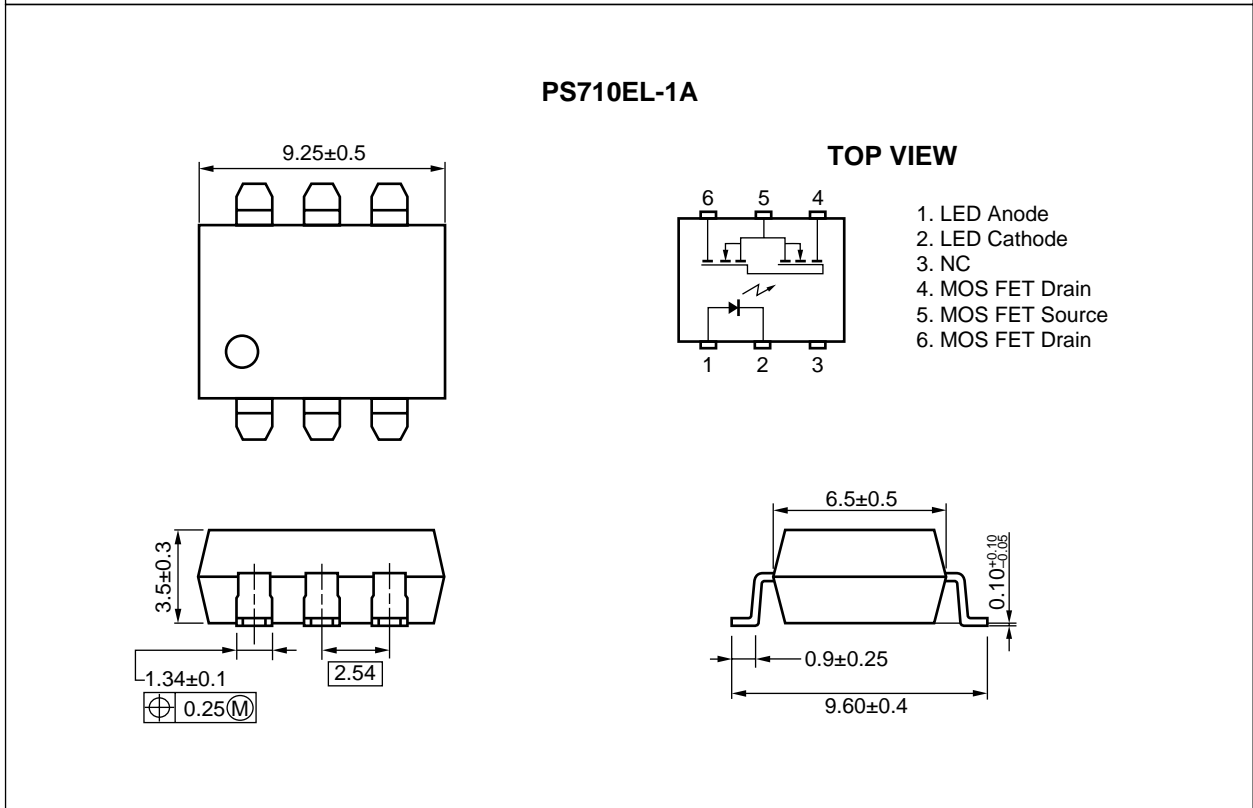
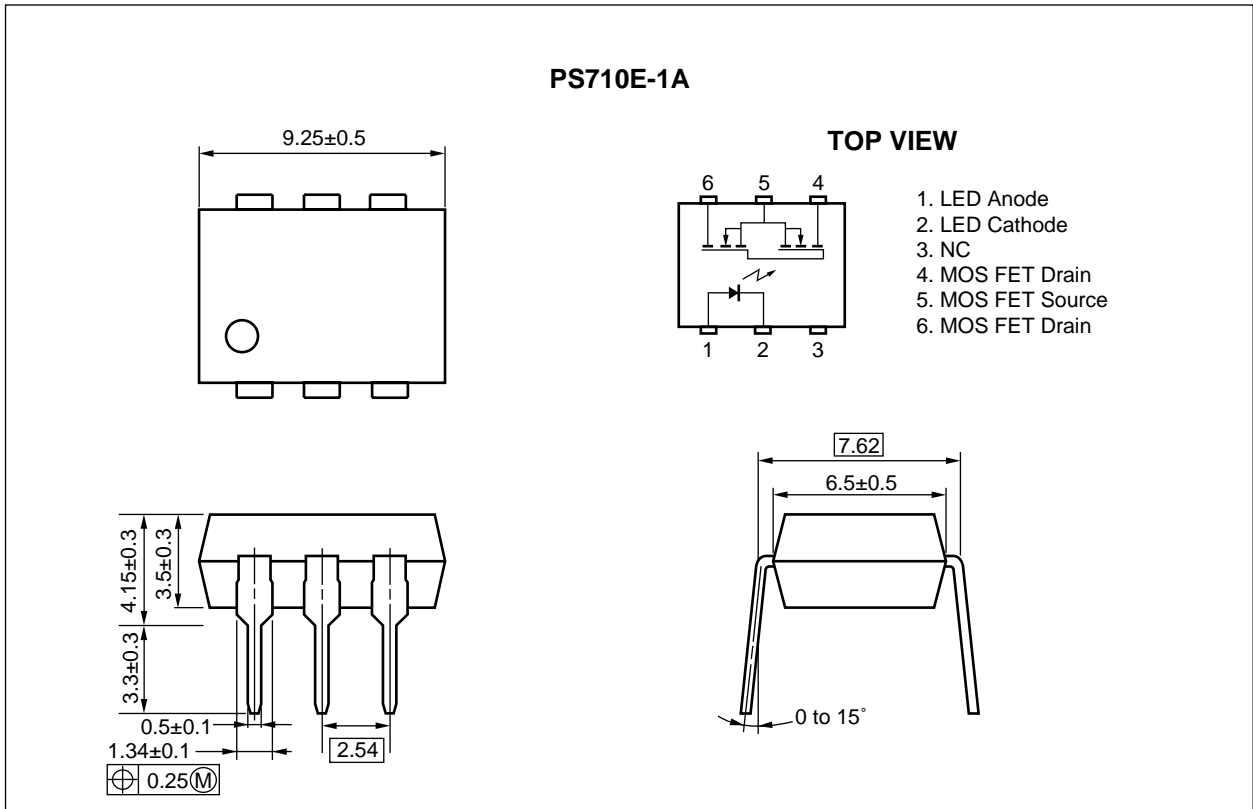
- Low on-state resistance ($R_{on} = 0.08 \Omega$ TYP.)
- Large continuous load current ($I_L = 2.0 A$)
- 1 channel type (1 a output)
- Low LED operating current ($I_F = 2 mA$)
- Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- Low offset voltage
- PS710EL-1A: Surface mount type

APPLICATIONS

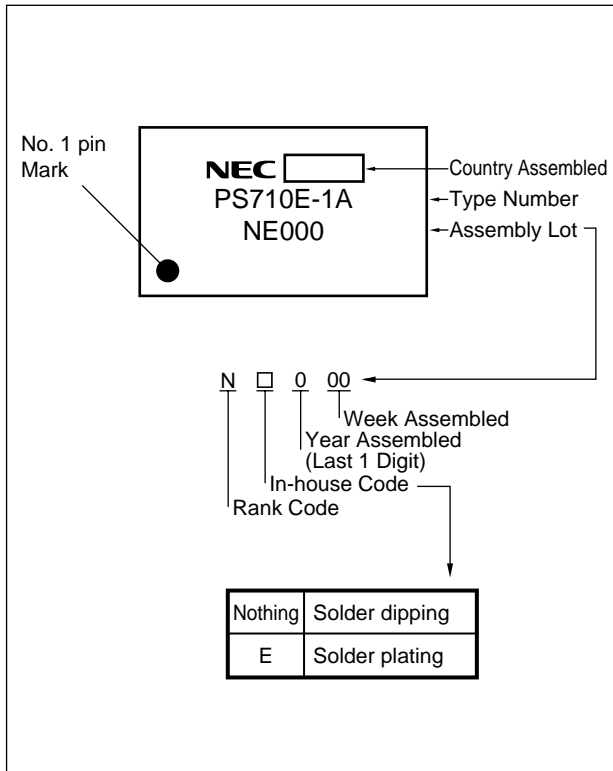
- Measurement equipment
- FA equipment

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PACKAGE DIMENSIONS (UNIT: mm)



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^{*1}
PS710E-1A	6-pin DIP	Magazine case 50 pcs	PS710E-1A
PS710EL-1A			PS710EL-1A
PS710EL-1A-E3		Embossed tape 1 000 pcs/reel	
PS710EL-1A-E4			

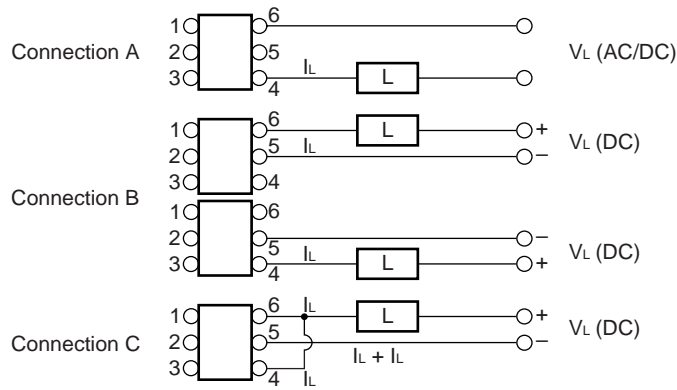
*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	I _F	50	mA	
	Reverse Voltage	V _R	5.0	V	
	Power Dissipation	P _D	50	mW	
	Peak Forward Current ^{*1}	I _{FP}	1	A	
MOS FET	Load Voltage	V _L	80	V	
	Continuous Load Current ^{*2}	Connection A	I _L	2.0	A
		Connection B		3.0	
		Connection C		4.0	
	Pulse Load Current ^{*3} (AC/DC Connection)	I _{LP}	4.0	A	
Power Dissipation	P _D	600	mW		
Isolation Voltage ^{*4}		BV	1 500	V _{r.m.s.}	
Total Power Dissipation		P _T	650	mW	
Operating Ambient Temperature		T _A	-40 to +85	°C	
Storage Temperature		T _{stg}	-40 to +100	°C	

*1 PW = 100 μs, Duty Cycle = 1%

*2 Conditions: I_F ≥ 2 mA. The following types of load connections are available.



*3 PW = 100 ms, 1 shot

*4 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output

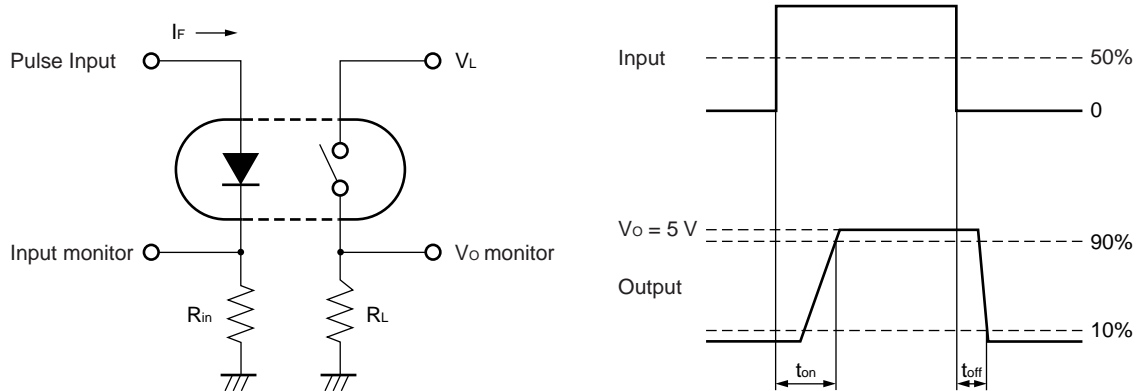
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I _F	2	10	20	mA
LED Off Voltage	V _F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.2	1.4	V
	Reverse Current	I _R	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I _{Loff}	V _D = 80 V			50	nA
	Output Capacitance	C _{out}	V _D = 0 V, f = 1 MHz		480		pF
Coupled	LED On-state Current	I _{Fon}	I _L = 2.0 A			2.0	mA
	On-state Resistance	R _{on}	I _F = 10 mA, I _L = 2.0 A, t ≤ 10 ms		0.083	0.15	Ω
	Turn-on Time ^{*1,2}	t _{on}	I _F = 10 mA, V _O = 5 V, R _L = 500 Ω,		1.0	2.0	ms
	Turn-off Time ^{*1,2}	t _{off}	PW ≥ 10 ms		0.02	0.2	
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}		10 ⁹		Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz			0.5	pF

***1 Test Circuit for Switching Time**

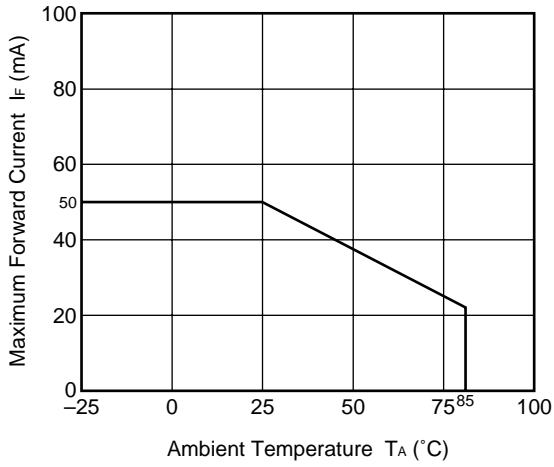


***2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

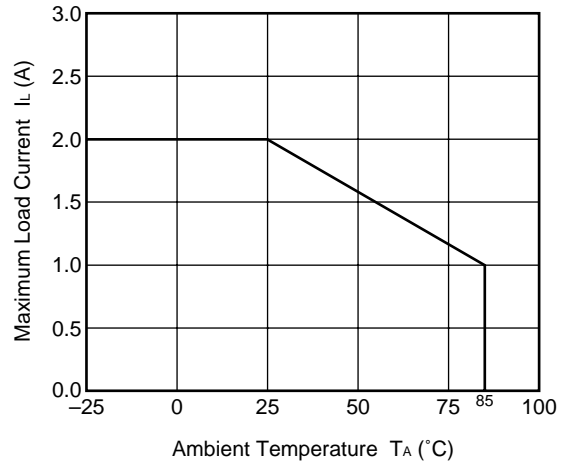
Be aware that when the device operates with an input-pulse width of under 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

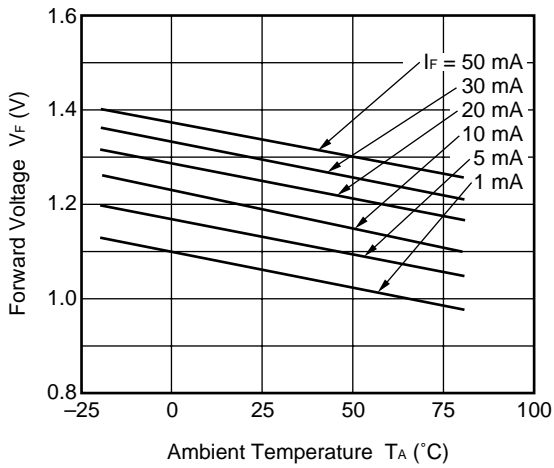
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



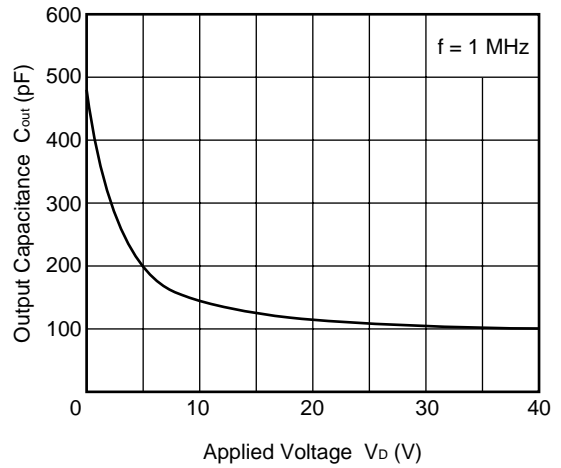
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



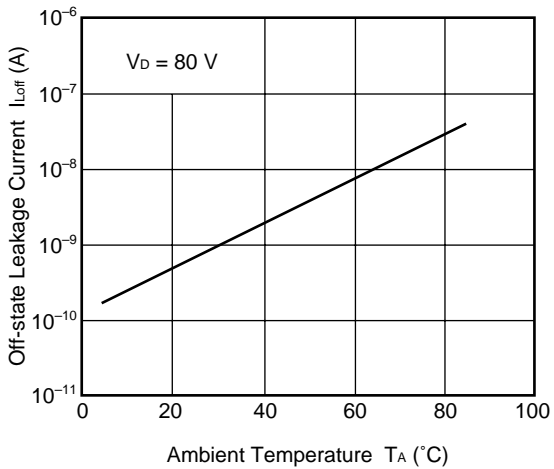
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



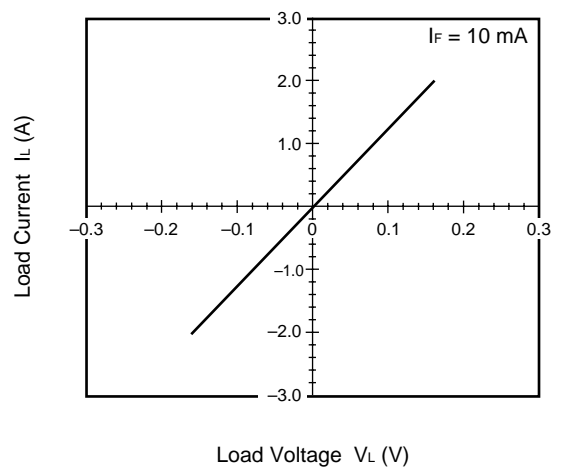
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



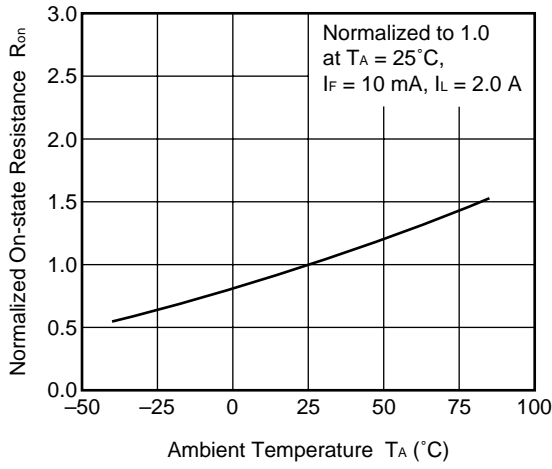
OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



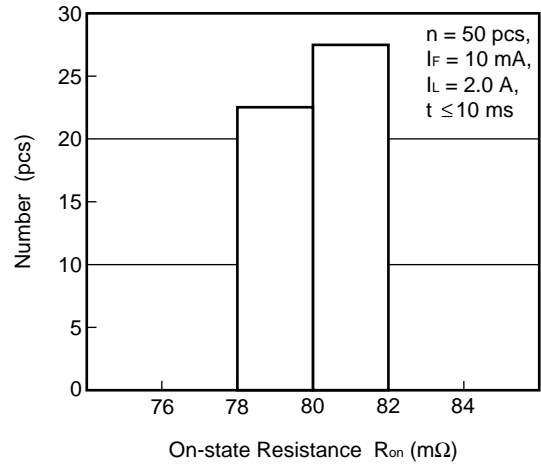
LOAD CURRENT vs. LOAD VOLTAGE



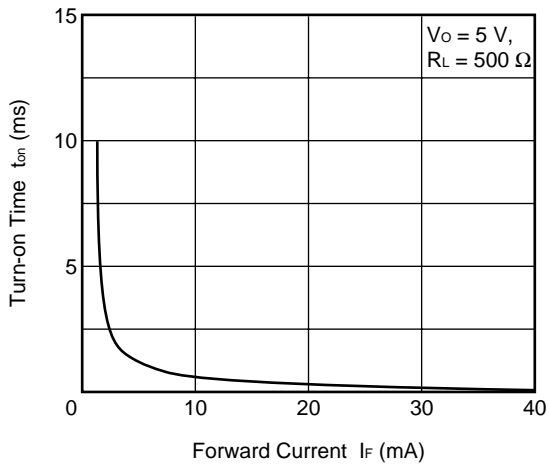
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



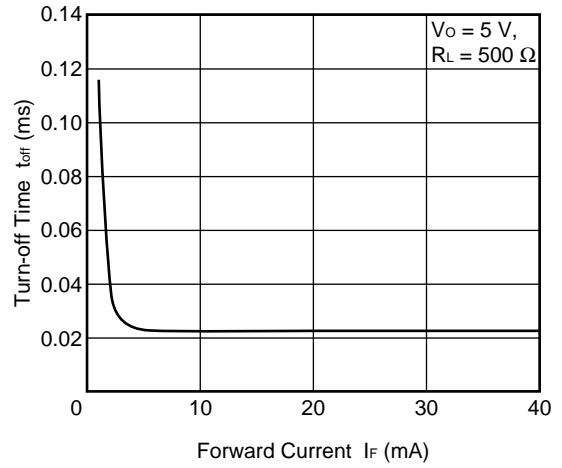
ON-STATE RESISTANCE DISTRIBUTION



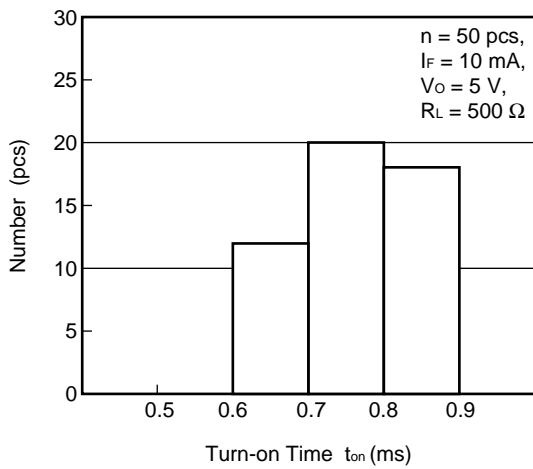
TURN-ON TIME vs. FORWARD CURRENT



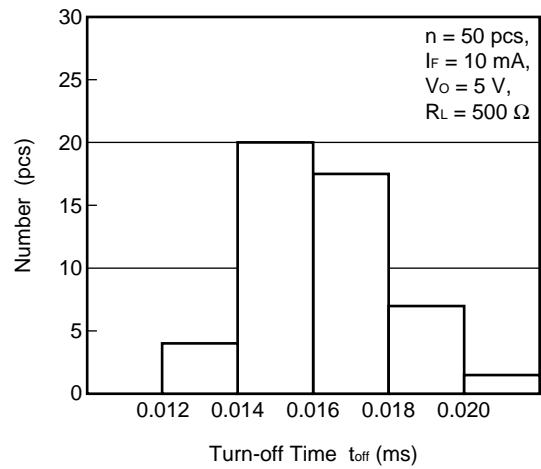
TURN-OFF TIME vs. FORWARD CURRENT



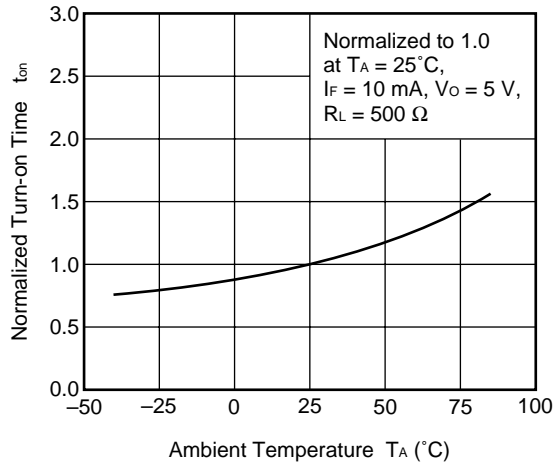
TURN-ON TIME DISTRIBUTION



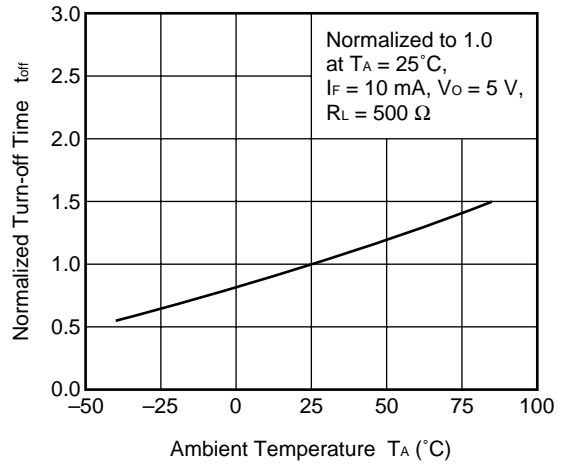
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



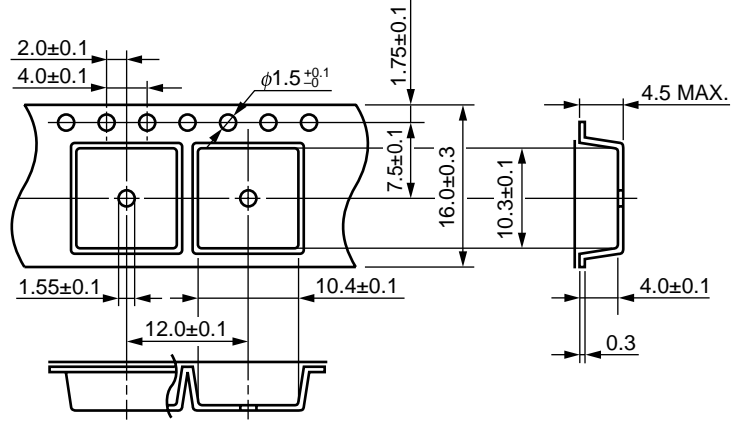
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



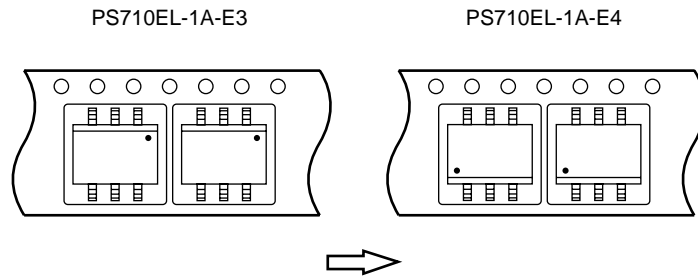
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

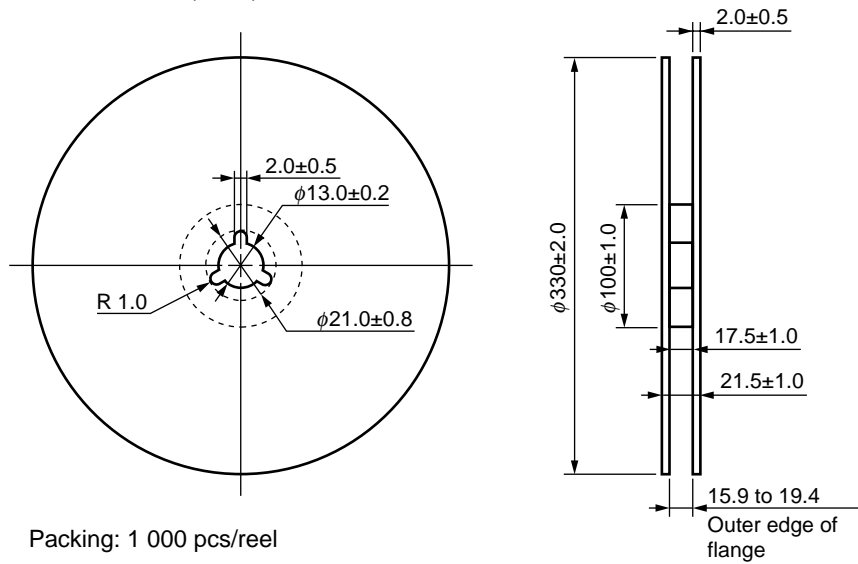
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

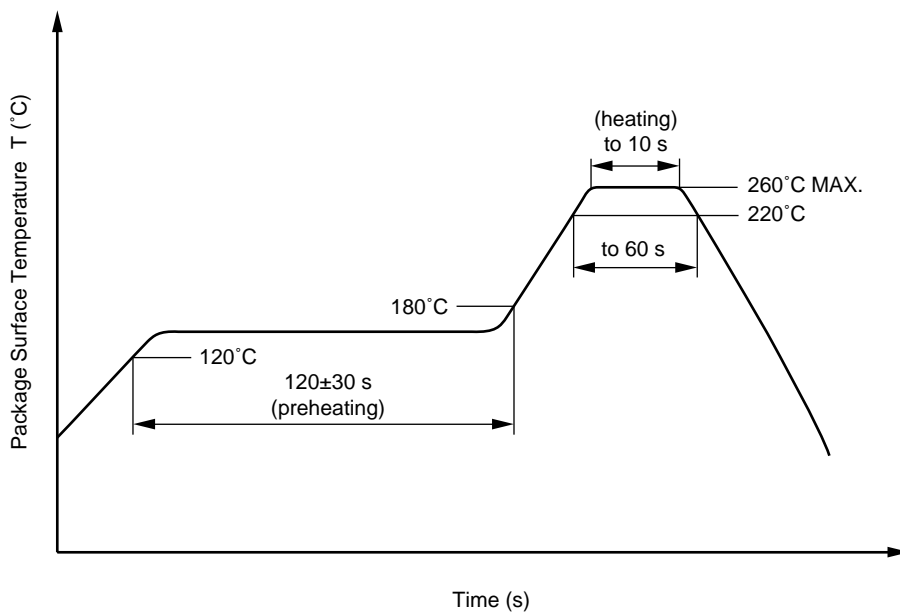


RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

<p>Caution</p>	<p>GaAs Products</p>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► **Business issue**

NEC Compound Semiconductor Devices, Ltd.

5th Sales Group, Sales Division TEL: +81-3-3798-6372 FAX: +81-3-3798-6783 E-mail: salesinfo@csd-nec.com

NEC Compound Semiconductor Devices Hong Kong Limited

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
 Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
 Korea Branch Office TEL: +82-2-528-0301 FAX: +82-2-528-0302

NEC Electron Devices European Operations <http://www.nec.de/>

TEL: +49-211-6503-101 FAX: +49-211-6503-487

California Eastern Laboratories, Inc. <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279

► **Technical issue**

NEC Compound Semiconductor Devices, Ltd. <http://www.csd-nec.com/>

Sales Engineering Group, Sales Division
 E-mail: techinfo@csd-nec.com FAX: +81-44-435-1918